

Low Voltage Dual D-Type Positive Edge-Triggered Flip-Flop 74LVX74

General Description

The LVX74 is a dual D-type flip-flop with Asynchronous Clear and Set inputs and complementary (Q, \overline{Q}) outputs. Information at the input is transferred to the outputs on the positive edge of the clock pulse. After the Clock Pulse input threshold voltage has been passed, the Data input is locked out and information present will not be transferred to the outputs until the next rising edge of the Clock Pulse input.

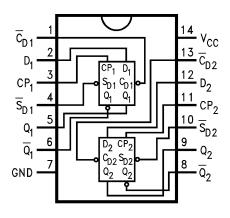
Asynchronous Inputs:

- LOW Input to \overline{S}_D (Set) Sets Q to HIGH Level
- LOW Input to \overline{C}_D (Clear) Sets Q to LOW Level
- Clear and Set are Independent of Clock
- Simultaneous LOW on \overline{C}_D and \overline{S}_D Makes Both Q and \overline{Q} HIGH

Features

- Input Voltage Level Translation from 5 V to 3 V
- Ideal for Low Power/Low Noise 3.3 V Applications
- Guaranteed Simultaneous Switching Noise Level and Dynamic Threshold Performance
- Pb-Free, Halogen Free/BFR Free and RoHS Compliant

Connection Diagram



Pin Description

Pin Names	Description
D ₁ , D ₂	Data Inputs
CP ₁ , CP ₂	Clock Pulse Inputs
$\overline{C}_{D1}, \overline{C}_{D2}$	Direct Clear Inputs
$\overline{S}_{D1,}\overline{S}_{D2}$	Direct Set Inputs
$Q_1, \overline{Q}_1, Q_2, \overline{Q}_2$	Outputs

1



TSSOP-14 WB CASE 948G

MARKING DIAGRAM



XXX = Specific Device Code A = Assembly Location

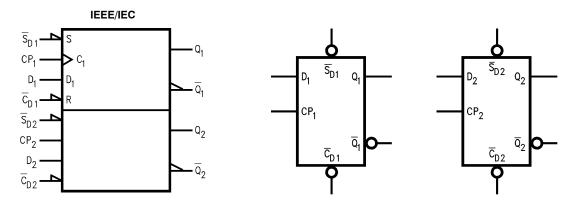
L = Wafer Lot
Y = Year
W = Work Week
Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

Logic Symbols



Truth Table

(Each Half)

	Inp	Out	outs		
SD	<u>C</u> D	СР	D	Q	Q
L	Н	Х	Х	Н	L
Н	L	Х	Х	L	Н
L	L	Х	Х	Н	Н
Н	Н	~	Н	Н	L
Н	Н	~	L	L	Н
Н	Н	L	Х	Q_0	\overline{Q}_0

H = HIGH Voltage Level

L = LOW Voltage Level

 $\begin{array}{l} \text{X = Immaterial} \\ \text{\checkmark = LOW-to-HIGH Clock Transition} \\ \text{Q_0 $(\overline{\mathbb{Q}}_0)$ = Previous Q $(\overline{\mathbb{Q}})$ before LOW-to-HIGH Transition of Clock} \\ \end{array}$

ABSOLUTE MAXIMUM RATINGS

Symbol	Para	meter	Rating	Unit
V _{CC}	Supply Voltage		−0.5 to +6.5	V
I _{IK}	DC Input Diode Current, $V_I = -0.5 \text{ V}$	DC Input Diode Current, V _I = -0.5 V		mA
V _I	DC Input Voltage	DC Input Voltage		V
lok	DC Output Diode Current	V _O = -0.5 V	-20	mA
		$V_{O} = V_{CC} + 0.5 V$	+20	mA
V _O	DC Output Voltage		-0.5 to V _{CC} + 0.5	V
Io	DC Output Source or Sink Current		±25	mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current		±50	mA
T _{STG}	Storage Temperature		-65 to +150	°C
P _D	Power Dissipation		833	mW

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS (Note 1)

Symbol	Parameter	Rating	Unit
V _{CC}	Supply Voltage	2.0 to 3.6	V
VI	Input Voltage	0 to 5.5	V
Vo	Output Voltage	0 to V _{CC}	V
T _A	Operating Temperature	-40 to +85	°C
Δt / ΔV	Input Rise and Fall Time	0 to 100	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. Unused inputs must be held HIGH or LOW. They may not float.

74LVX74

DC ELECTRICAL CHARACTERISTICS

				T _A = 25°C			T _A = -40°	C to +85°C	
Symbol	Parameter	V _{CC} (V)	Conditions	Min	Тур	Max	Min	Max	Unit
V _{IH}	HIGH Level Input	2.0		1.5	-	-	1.5	-	V
	Voltage	3.0	1	2.0	-	-	2.0	-	
		3.6		2.4	-	-	2.4	-	
V_{IL}	LOW Level Input	2.0		-	-	0.5	-	0.5	V
	Voltage	3.0		_	-	8.0	-	0.8	
		3.6	1	_	-	0.8	-	0.8	
V _{OH}	HIGH Level Output Voltage	2.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -50 \mu A$	1.9	2.0	_	1.9	_	V
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -50 \mu A$	2.9	3.0	_	2.9	_	
			$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -4 \text{ mA}$	2.58	_	_	2.48	_	
V _{OL}	LOW Level Output Voltage	2.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 50 \mu A$	-	0.0	0.1	-	0.1	V
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 50 \mu A$	-	0.0	0.1	-	0.1	
			$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 4 \text{ mA}$	-	_	0.36	-	0.44	
I _{IN}	Input Leakage Current	3.6	V _{IN} = 5.5 V or GND	-	-	±0.1	-	±1.0	μΑ
I _{CC}	Quiescent Supply Current	3.6	V _{IN} = V _{CC} or GND	-	_	2.0	-	20.0	μΑ

NOISE CHARACTERISTICS (Note 2)

				T _A = 25°C		
Symbol	Characteristic	V _{CC} (V)	C _L (pF)	Тур	Limit	Unit
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}	3.3	50	0.3	0.5	V
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}	3.3	50	-0.3	-0.5	V
V_{IHD}	Minimum HIGH Level Dynamic Input Voltage	3.3	50	-	2.0	V
V_{ILD}	Maximum LOW Level Dynamic Input Voltage	3.3	50	-	0.8	V

^{2.} Input $t_r = t_f = 3.0 \text{ ns}$

74LVX74

AC ELECTRICAL CHARACTERISTICS

					T _A = 25°C		$T_A = -40$) to 85°C	
Symbol	Parameter	V _{CC} (V)	C _L (pF)	Min	Тур	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	Propagation Delay CP_n to Q_n or \overline{Q}_n	2.7	15 50	-	7.3 9.8	15.0 18.5	1.0 1.0	18.5 22.0	ns
		3.3 ± 0.3	15 50	- -	5.7 8.2	9.7 13.2	1.0 1.0	11.5 15.0	
t _{PLH} , t _{PHL}	$\frac{\text{Propagation Delay}}{C_{Dn} \text{ to } \overline{S}_{Dn} \text{ to } Q_n \text{ or } \overline{Q}_n}$	2.7	15 50	- -	8.4 10.9	15.6 19.1	1.0 1.0	18.5 22.0	ns
		3.3 ± 0.3	15 50	- -	6.6 9.1	10.1 13.6	1.0 1.0	12.0 15.5	
t _W	CP_n or \overline{C}_{Dn} or \overline{S}_{Dn}	2.7	=	8.5	-	-	10.0	-	ns
	Pulse Width	3.3 ± 0.3	=	6.0	-	-	7.0	-	
t _S	Setup Time, D _n to CP _n	2.7	-	8.0	-	-	9.5	-	ns
		3.3 ± 0.3	-	5.5	-	-	6.5	-	
t _H	Hold Time, D _n to CP _n	2.7	-	0.5	-	-	0.5	-	ns
		3.3 ± 0.3	-	0.5	-	-	0.5	-	
t _{REC}	Recovery Time,	2.7	-	6.5	-	-	7.5	-	ns
	$\overline{\mathbb{C}}P_n$ or $\overline{\mathbb{S}}_Dn$ to $\mathbb{C}P_n$	3.3 ± 0.3	-	5.0	-	-	5.0	-	
f _{MAX}	Maximum Clock Frequency	2.7	15 50	55 45	135 60	- -	50 40	- -	MHz
		3.3 ± 0.3	15 50	95 60	145 85	- -	80 50	- -	
t _{OSLH} ,	Output to Output Skew	2.7	50	-	-	1.5	-	1.5	ns
toshl	(Note 3)	3.3		-	-	1.5	_	1.5	

^{3.} Parameter guaranteed by design toslh = |tplhm-tplhn|, toshl = |tphlm-tphln|

CAPACITANCE

		T _A = 25°C		T _A = -40			
Symbol	Parameter	Min	Тур	Max	Min	Max	Unit
C _{IN}	Input Capacitance	-	4	10	-	10	pF
C _{PD}	Power Dissipation Capacitance (Note 4)	-	25	_	_	-	рF

^{4.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(opr.)} = \frac{C_{PD} \times V_{CC} \times f_{IN} \times I_{CC}}{2 \text{ (per F/F)}}$

ORDERING INFORMATION

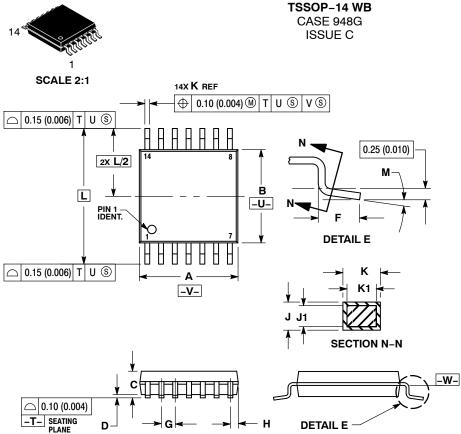
Device	Package	Marking	Shipping [†]
74LVX74MTCX	TSSOP-14	LVX 74	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*-}Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

DATE 17 FEB 2016





- NOTES.

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD
- FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 DIMENSION B DOES NOT INCLUDE
- INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION SHALL
- INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.

 TERMINAL NUMBERS ARE SHOWN FOR DEEEDENIC OMITY.
- REFERENCE ONLY.
 DIMENSION A AND B ARE TO BE
- DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026	BSC
Н	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40	BSC	0.252 BSC	
М	0°	8 °	0 °	8 °

GENERIC MARKING DIAGRAM*



= Assembly Location

L = Wafer Lot = Year

= Work Week W = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED SOLDERING FOOTPRINT*

-	7.06
1	
	-
	U 0.65 PITCH
↓ □	The state of the s
14X 0.36	
0.36 - 1.26	DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98ASH70246A	Electronic versions are uncontrolled except when accessed directly from the Document Repos Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.			
DESCRIPTION:	TSSOP-14 WB		PAGE 1 OF 1		

onsemi and ONSEMI. are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. **onsemi** makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, Onsemi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales